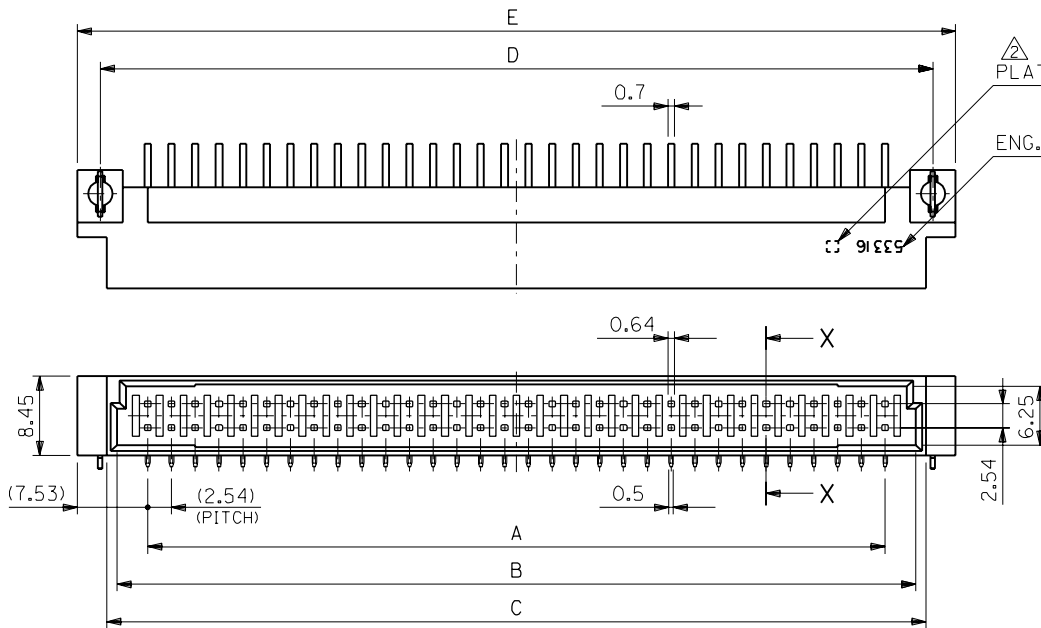


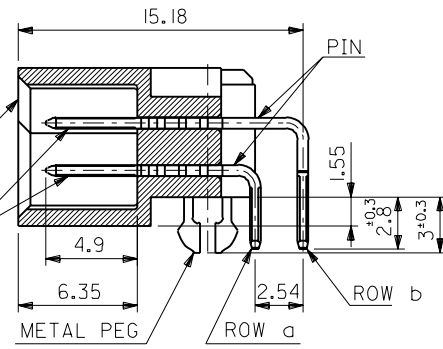
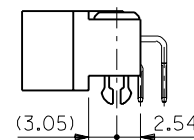
ENG. NO. SD-53316-\*\*\*\*  
 EDP NO.  
 DIMENSIONS IN METRIC DO NOT SCALE DRAWING



PLATING INDICATION NO.

ENG. NO.

GOLD PLATING AREA (WHOLE SURFACE)



SECT. X-X (SCALE: 4-1)

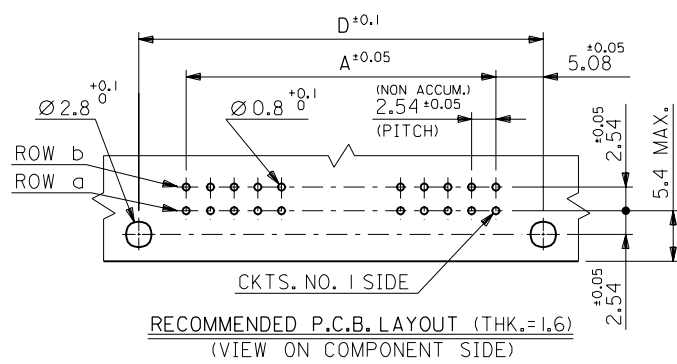
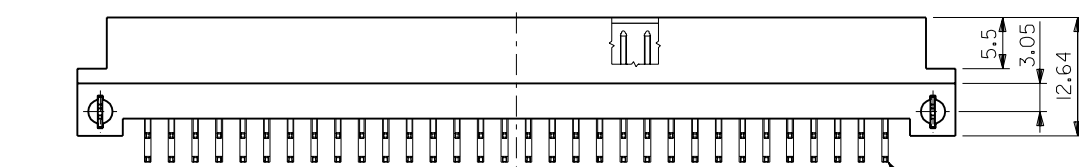
NOTES: 1. MATERIAL  
 HEADER: GLASS FILLED P.B.T. (WHITE), UL94V-0  
 PIN: BRASS (t=0.58)  
 METAL PEG: PHOSPHOR BRONZE (t=0.48),  
 TIN-LEAD OVER COPPER PLATING

PLATING & PLATING INDICATION NUMBER

ENG. NO.	CONTACT AREA GOLD [µmMIN.]	SOLDER AREA TIN-LEAD [µmMIN.]	UNDER PLATE NICKEL [µmMIN.]	PLATING INDICATION NUMBER
53316-***3	0.76		1.0	3
53316-***2	0.5		1.0	2
53316-***1	0.3			1
53316-***0	0.1			0

3. MATE WITH: 52299, 52385, 52479, 52482 SERIES.

93.80	88.90	87.50	85.30	78.74	53316-064*	64
76.02	71.12	69.72	67.52	60.96	↑ -050*	50
68.40	63.50	62.10	59.90	53.34	↑ -044*	44
53.16	48.26	46.86	44.66	38.10	↑ -032*	32
37.92	33.02	31.62	29.42	22.86	↓ -020*	20
32.84	27.94	26.54	24.34	17.78	53316-016*	16
E	D	C	B	A	ENG. NO.	NO. OF CKTS.



RECOMMENDED P.C.B. LAYOUT (THK.=1.6) (VIEW ON COMPONENT SIDE)

角度 ANGLE	±3°
30以上 OVER	+0.3
10以上 30未滿 UNDER	+0.25
10未滿 UNDER	+0.2

材料 MATERIAL	仕上げ FINISH	適用電線範囲 WIRE RANGE	被覆外径 INS. RANGE
SEE NOTES	SEE NOTES	—H—	—H—

材料 MATERIAL	SEE NOTES	molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH	SEE NOTES	EDP. NO.	
適用電線範囲 WIRE RANGE	—H—	ENG. NO.	REV
被覆外径 INS. RANGE	—H—	SD-53316-****	A
DRAWN BY '90/8/27 S.MOCHIZUKI	CHK'D BY	TITLE 名称 2.54 B TO B CONN. RIGHT ANGLE HEADER ASS'Y WITH METAL PEG (DUAL ROW)	
APP'D BY	尺 度 SCALE 2 - 1		

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